

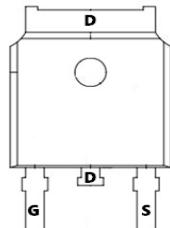
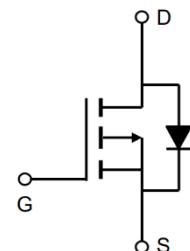
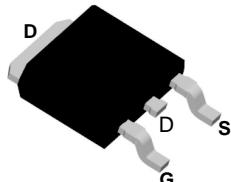
**TM100P03D**
**P -Channel Enhancement Mosfet**
**General Description**

- Low  $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

**Applications**

- Load switch
- PWM

**General Features**
 $V_{DS} = -30V$   $I_D = -100A$ 
 $R_{DS(ON)} = 3.6\text{ m}\Omega$  (typ.) @  $V_{GS} = -10V$ 

 100% UIS Tested  
 100%  $R_g$  Tested

**D:TO-252-3L**


Marking: 100P03

**Absolute Maximum Ratings (TC=25°C unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current TC=25°C	$I_D$	-100	A
TC=100°C		-67	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	-380	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	125	mJ
Total Power Dissipation	$P_D$	60	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{JA}$	50	°C/W
Thermal Resistance from Junction-to-Case	$R_{JC}$	1.58	°C/W

**Electrical Characteristics (T<sub>J</sub> = 25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-30	-	-	V
Gate-body Leakage current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current T <sub>J</sub> =25°C	I <sub>DSS</sub>	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V	-	-	-1	μA
T <sub>J</sub> =100°C			-	-	-100	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.0	-1.5	-2.5	V
Drain-Source On-Resistance <sup>4</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -30A	-	3.6	5.4	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -15A	-	5.5	6.2	
Forward Transconductance <sup>4</sup>	g <sub>fS</sub>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -30A	-	90	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1MHz	-	5270	-	pF
Output Capacitance	C <sub>oss</sub>		-	695	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	580	-	
Gate resistance	R <sub>g</sub>	f = 1MHz	-	4	-	Ω
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -15V, I <sub>D</sub> = -30A	-	146	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	21.5	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	39	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> = -10V, V <sub>DD</sub> = -15V, R <sub>G</sub> = 3Ω, I <sub>D</sub> = -30A	-	23	-	ns
Rise Time	t <sub>r</sub>		-	15	-	
Turn-Off Delay Time	t <sub>d(off)</sub>		-	129	-	
Fall Time	t <sub>f</sub>		-	28	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	V <sub>SD</sub>	I <sub>S</sub> = -30A, V <sub>GS</sub> = 0V	-	-	-1.2	V
Continuous Source Current   T <sub>C</sub> =25°C	I <sub>S</sub>	-	-	-	-100	A

Note :

1. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C
2. The EAS data shows Max. rating . The test condition is V<sub>DD</sub>= -25V, V<sub>GS</sub>= -10V, L= 0.1mH, I<sub>AS</sub>= -50A
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.

## Typical Characteristics

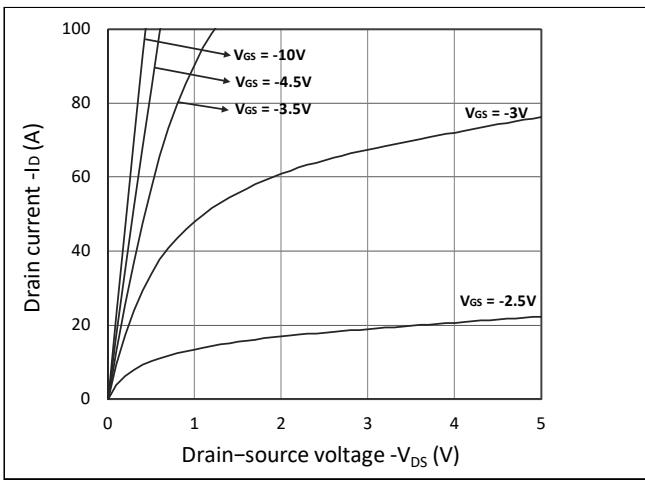


Figure 1. Output Characteristics

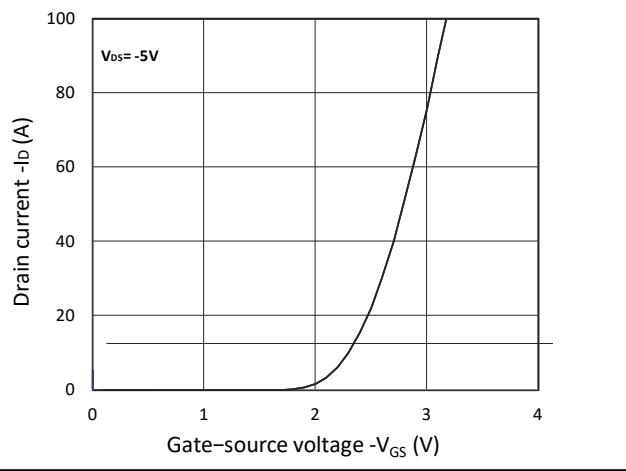


Figure 2. Transfer Characteristics

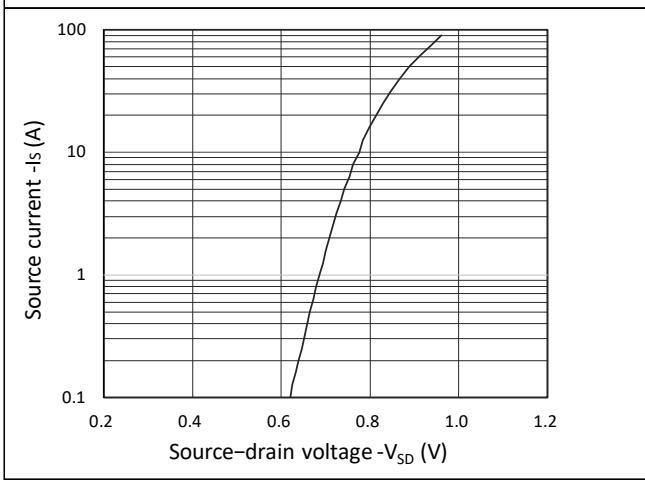


Figure 3. Forward Characteristics of Reverse

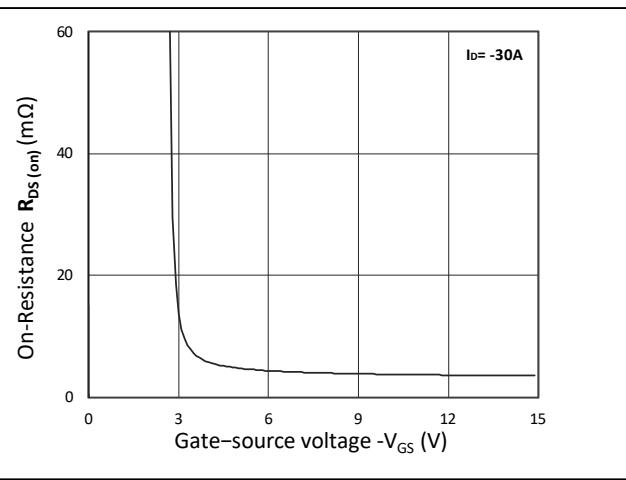


Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$

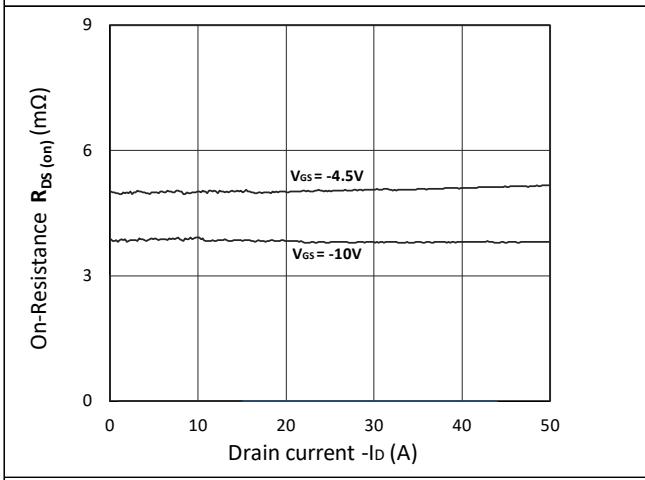


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

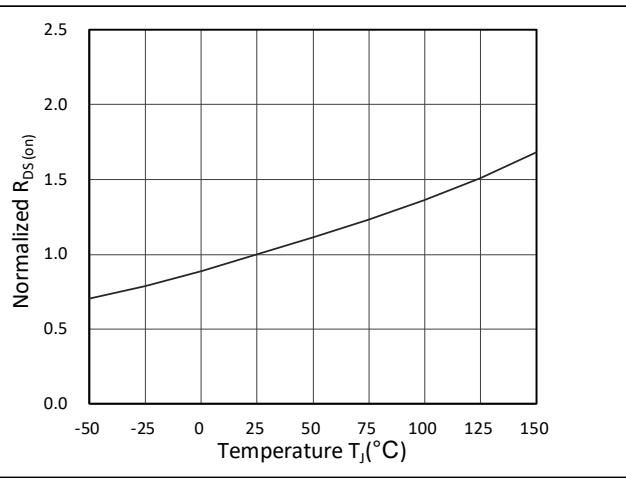


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

## TM100P03D

## P -Channel Enhancement Mosfet

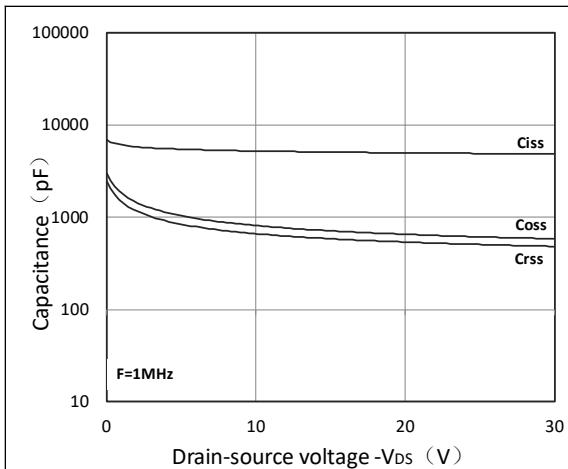


Figure 7. Capacitance Characteristics

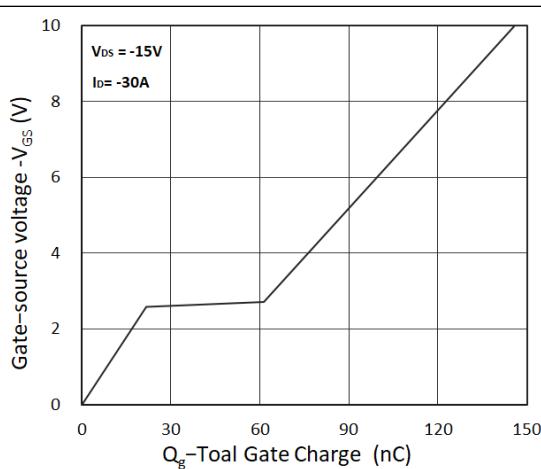


Figure 8. Gate Charge Characteristics

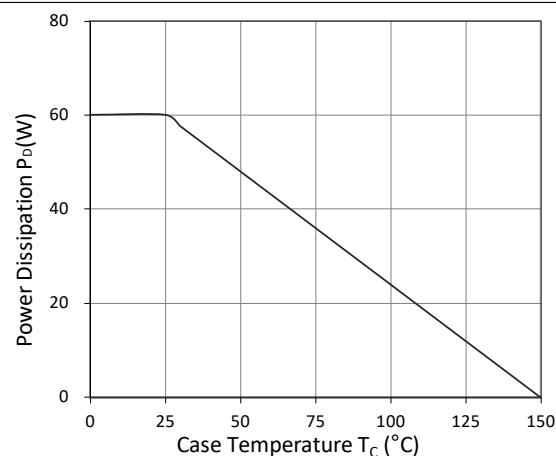


Figure 9. Power Dissipation

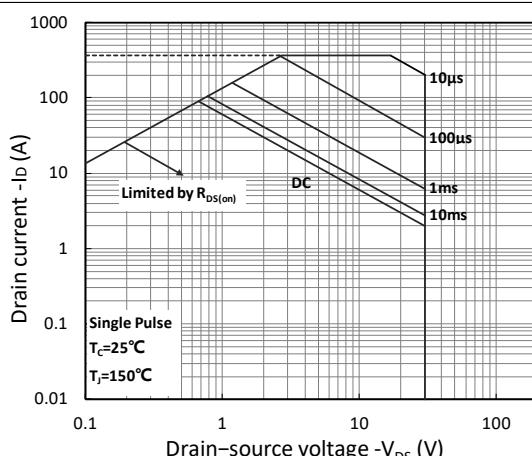


Figure 10. Safe Operating Area

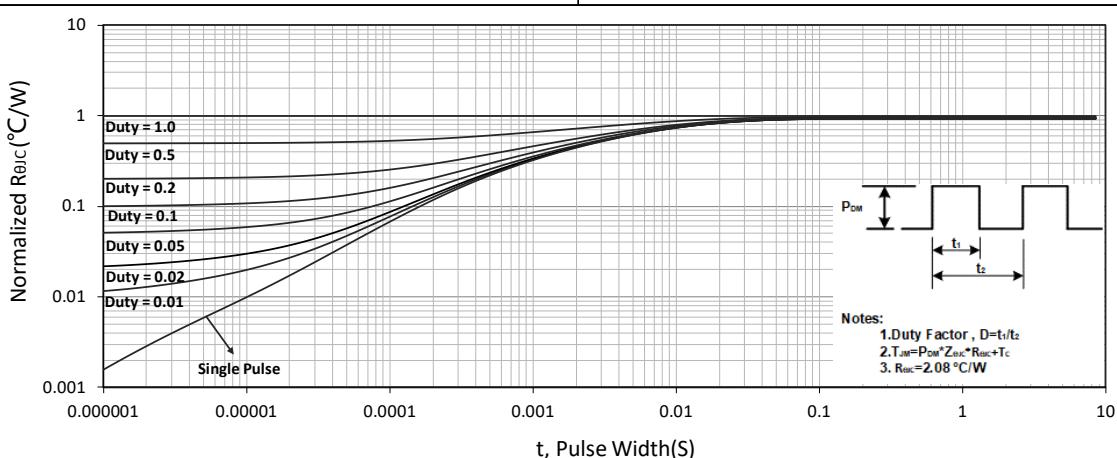


Figure 11. Normalized Maximum Transient Thermal Impedance

### Test Circuit

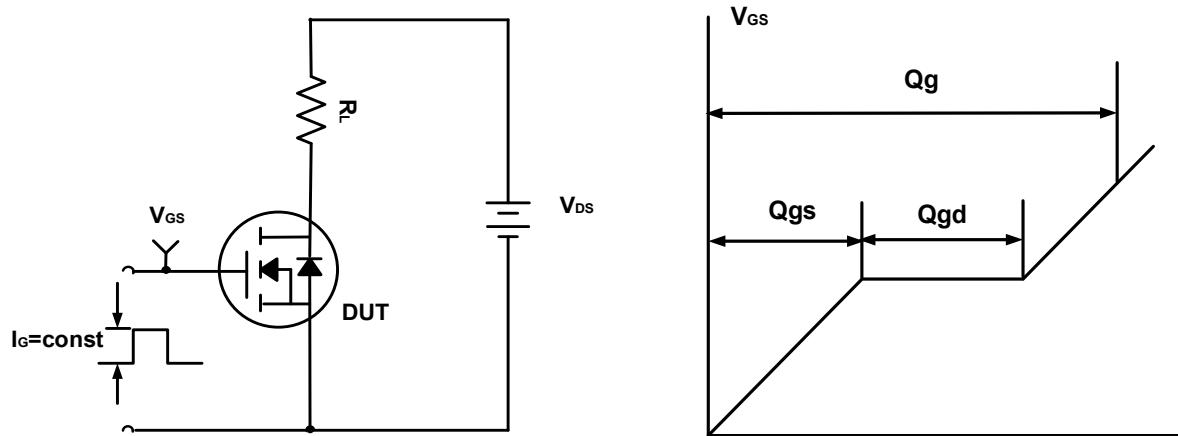


Figure A. Gate Charge Test Circuit & Waveforms

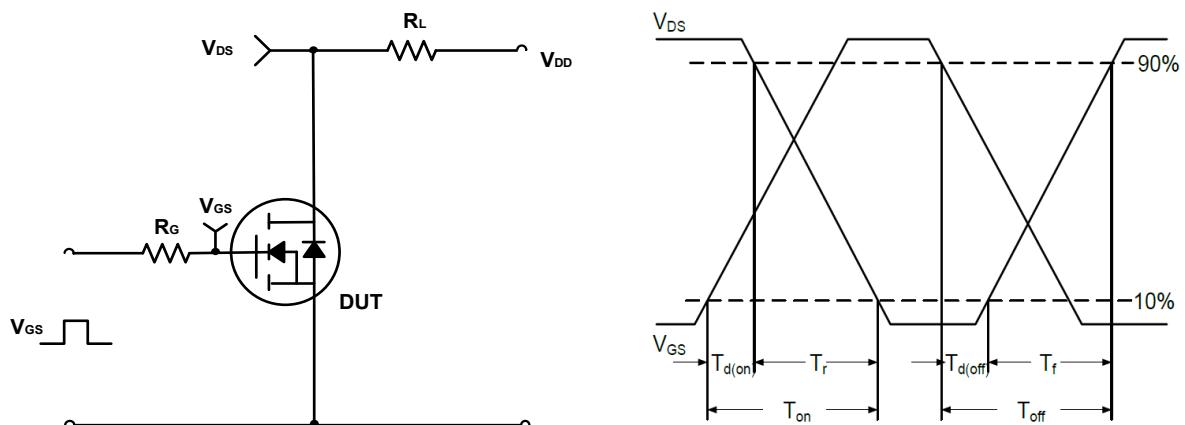


Figure B. Switching Test Circuit & Waveforms

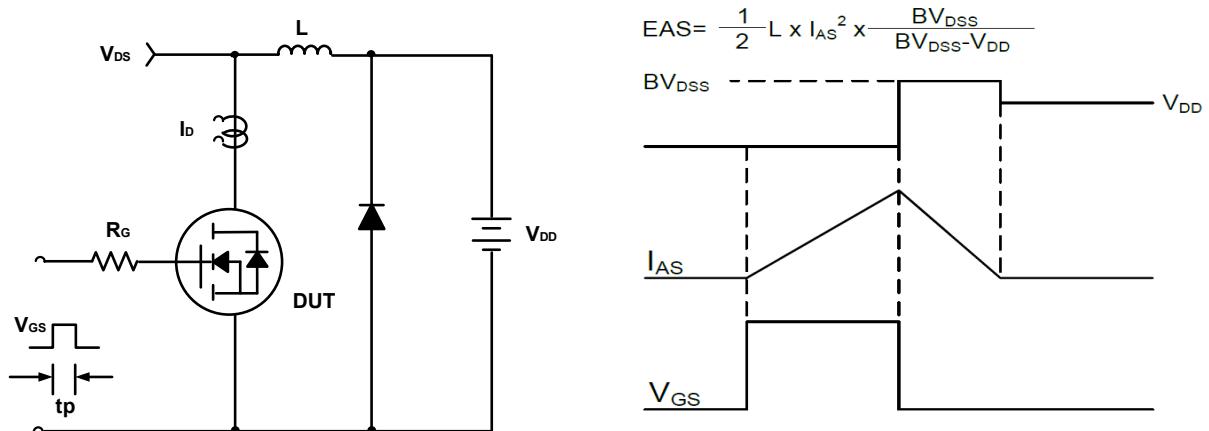
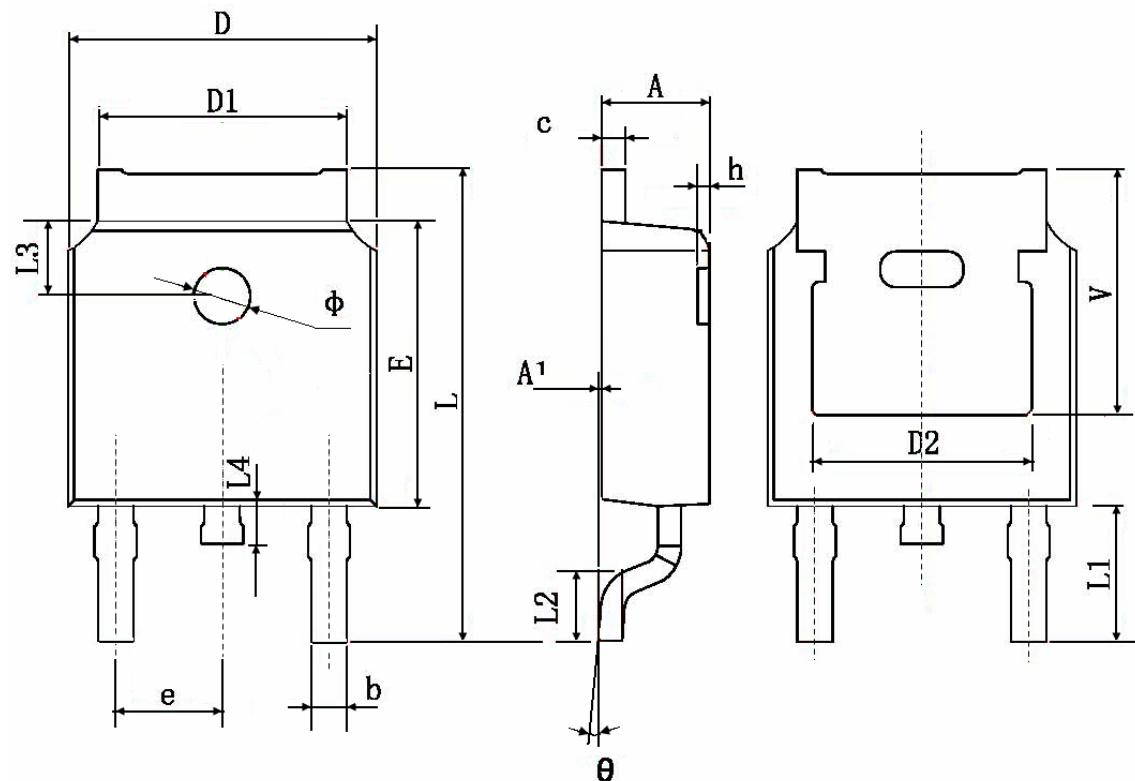


Figure C. Unclamped Inductive Switching Circuit & Waveforms

## Package Information:TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	